

# SN74HC139-Q1

## DUAL 2-LINE TO 4-LINE DECODER/DEMULTIPLEXER

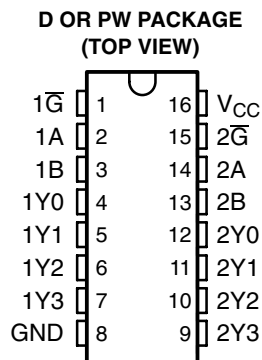
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- Qualified for Automotive Applications
- Targeted Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive up to Ten LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 10$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- ESD Protection Level per AEC-Q100 Classification
  - 2000-V (H2) Human-Body Model
  - 200-V (M3) Machine Model
  - 1000-V (C5) Charged-Device Model

### description/ordering information

The SN74HC139 device is designed for high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, this decoder can minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay time of this decoder and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The SN74HC139 device comprises two individual 2-line to 4-line decoders in a single package. The active-low enable ( $\bar{G}$ ) input can be used as a data line in demultiplexing applications. This decoder/demultiplexer features fully buffered inputs, each of which represents only one normalized load to its driving circuit.



### ORDERING INFORMATION<sup>†</sup>

T <sub>A</sub>	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – D	Reel of 2500	SN74HC139QDRQ1	HC139Q
	TSSOP – PW	Reel of 2000	SN74HC139QPWRQ1	HC139Q

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

<sup>‡</sup> Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

### FUNCTION TABLE

INPUTS			OUTPUTS			
$\bar{G}$	SELECT		Y0	Y1	Y2	Y3
	B	A				
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L



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**TEXAS  
INSTRUMENTS**

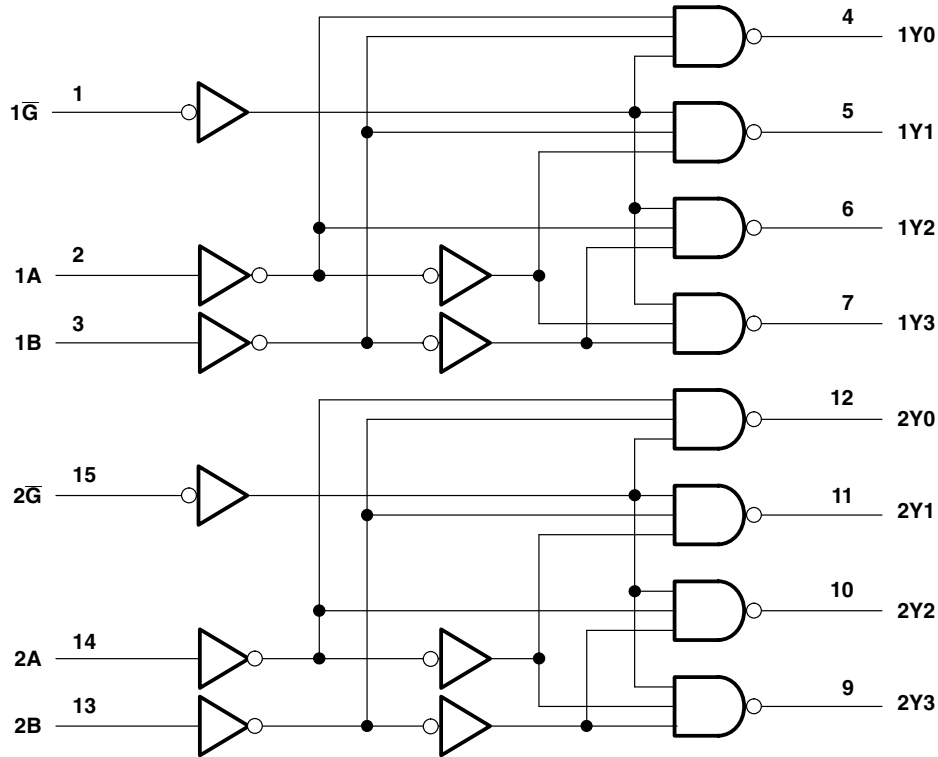
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# SN74HC139-Q1 DUAL 2-LINE TO 4-LINE DECODER/DEMULTIPLEXER

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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	73°C/W
PW package	108°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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### recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5		V
		V <sub>CC</sub> = 4.5 V	3.15		
		V <sub>CC</sub> = 6 V	4.2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5		V
		V <sub>CC</sub> = 4.5 V	1.35		
		V <sub>CC</sub> = 6 V	1.8		
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>		V
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 2 V	1000		ns
		V <sub>CC</sub> = 4.5 V	500		
		V <sub>CC</sub> = 6 V	400		
T <sub>A</sub>	Operating free-air temperature	-40	125		°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998	1.9	1.9			V
			4.5 V	4.4	4.499	4.4	4.4			
			6 V	5.9	5.999	5.9	5.9			
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3	3.7	3.84			
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8	5.2	5.34			
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1	0.1	0.1		V
			4.5 V		0.001	0.1	0.1	0.1		
			6 V		0.001	0.1	0.1	0.1		
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26	0.4	0.33		
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26	0.4	0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V		±0.1	±100	±1000	±1000		nA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V			8	160	80		μA	
C <sub>i</sub>		2 V to 6 V		3	10	10	10		pF	



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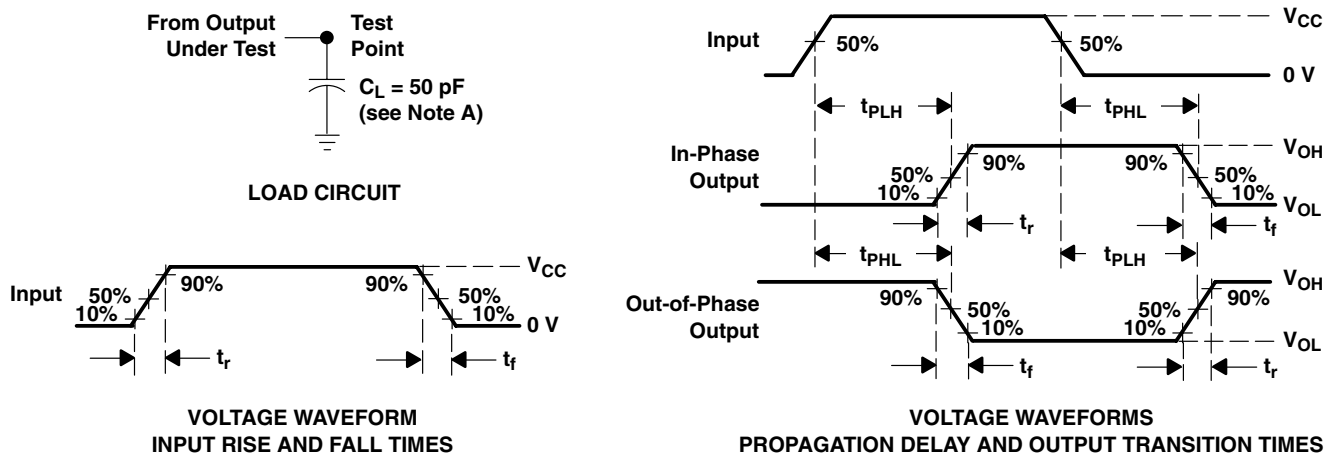
switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ TO $125^\circ\text{C}$		$T_A = -40^\circ\text{C}$ TO $85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	Y	2 V		47	175		255		220	ns
			4.5 V		14	35		51		44	
			6 V		12	30		44		38	
	$\bar{G}$	Y	2 V		39	175		255		220	
			4.5 V		11	35		51		44	
			6 V		10	30		44		38	
$t_t$		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per decoder	No load	25	pF

### PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - C. The outputs are measured one at a time, with one input transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC139QDRG4Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC139Q	<a href="#">Samples</a>
SN74HC139QDRQ1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC139Q	<a href="#">Samples</a>
SN74HC139QPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC139Q	<a href="#">Samples</a>
SN74HC139QPWRQ1	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HC139Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74HC139-Q1 :**

- Catalog: [SN74HC139](#)
- Military: [SN54HC139](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC139QDRQ1	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC139QPWRG4Q1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC139QPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC139QPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC139QDRQ1	SOIC	D	16	2500	356.0	356.0	35.0
SN74HC139QPWRG4Q1	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC139QPWRQ1	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC139QPWRQ1	TSSOP	PW	16	2000	356.0	356.0	35.0



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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